IPC ASSOCIATION ELECTRONICS	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information			
Supplier	Information														
Company name*				Company unique ID			Unique ID Authority				Response Date*				
onsemi											2024-05-12				
Contact Na	me	Title - Contact			]	Phone - Contact*				Email - Contact*					
Product-E	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorized	Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
Product-E	nv-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Da	ite Versi	on 1	Manufacturing Site		Weight*	UOM	Unit Type	
		FOD2711AS 8PW E-AMP TR S		SMD		2024-05-12 LITEONFG		4	197.66	mg	Each				
Manufac	turing Proccess Informa	ntion						1							
7	Terminal Plating / Grid Array Material Te			Germinal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperat		y Temperatu	ture Max Time at Peak Temper		ure Nur	nber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy			1			260		C	30	secon	ds 3				
Comments															
evel 1 - ma	ximum time at peak temperat	ure during sol	dering is 10-3	0 seconds											
or more ir	nformation regarding material	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight Unit of Measure Level Substance		Substance	CAS	Exempt	Weight	Unit of Measure	
Coupling Gel	0.45	mg	Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.045	mg
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		0.405	mg
Die	4.011	mg	В	Gallium Arsenide (AsGa)	1303-00-0		0.281	mg
			Supplier	Silicon (Si)	7440-21-3		3.73	mg
Die Attach	0.251	mg	Supplier	Silver (Ag)	7440-22-4		0.188	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.063	mg
Lead Frame	112.468	mg	Supplier	Silver (Ag)	7440-22-4		0.709	mg
			Supplier	Zinc (Zn)	7440-66-6		0.135	mg
			Supplier	Iron (Fe)	7439-89-6		2.59	mg
			Supplier	Copper (Cu)	7440-50-8		109	mg
			Supplier	Phosphorus (P)	7723-14-0		0.034	mg
Mold Compound-Black	375.6	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		15	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		86.3001	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		11.3	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		262.9999	mg
Plating	2.88	mg	Supplier	Tin (Sn)	7440-31-5		2.88	mg
Wire Bond - Au	2.0	mg	Supplier	Gold (Au)	7440-57-5		2	mg